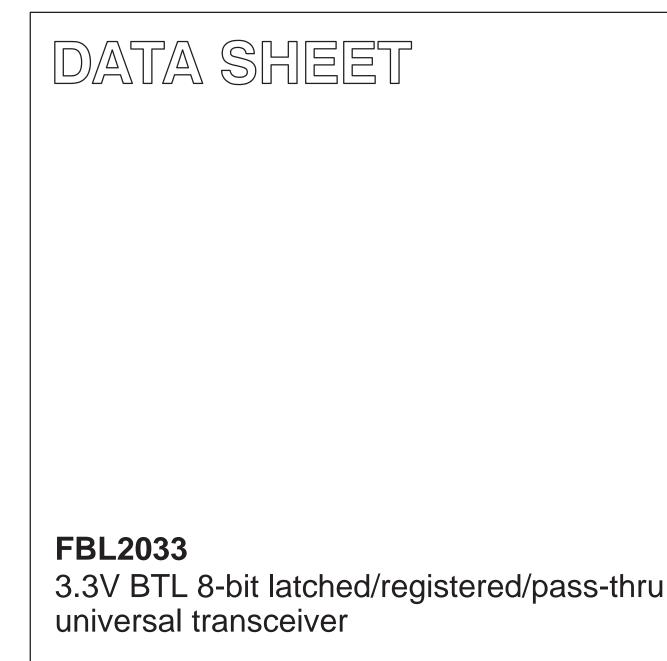
## INTEGRATED CIRCUITS



Product specification

1999 Apr 15

IC23 data handbook

## **Philips Semiconductors**





## FBL2033

#### **FEATURES**

- 8-bit transceivers
- Latched, registered or straight through in either A to B or B to A path
- Drives heavily loaded backplanes with equivalent load impedances down to 10Ω.
- High drive 100mA BTL Open Collector drivers on B-port
- Allows incident wave switching in heavily loaded backplane buses
- Reduced BTL voltage swing produces less noise and reduces power consumption
- Built-in precision band-gap reference provides accurate receiver thresholds and improved noise immunity

- Compatible with IEEE Futurebus+ or proprietary BTL backplanes
- Each BTL driver has a dedicated Bus GND for a signal return
- Controlled output ramp and multiple GND pins minimize ground bounce
- Glitch-free power up/power down operation
- Low I<sub>CC</sub> current
- Tight output skew
- Supports live insertion
- Pins for the optional JTAG boundary scan function are provided
- High density packaging in plastic Quad Flatpack
- 5V compatible I/O on A-port

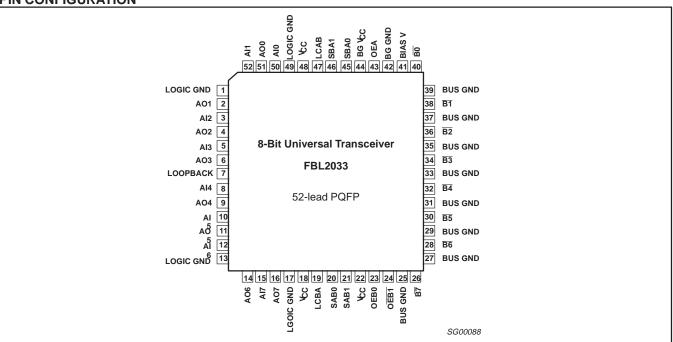
### QUICK REFERENCE DATA

SYMBOL	PARAME	TER	TYPICAL	UNIT
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay Aln to Bn	3.0 3.0	ns	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay Bn to AOn	5.0 5.3	ns	
C <sub>OB</sub>	Output capacitance (B0 – Bn only)	6	pF	
I <sub>OL</sub>	Output current (B0 – Bn only)		100	mA
lee	I <sub>CC</sub> Supply current	AIn to Bn outputs Low outputs High	9 14	mA
		Bn to AOn (outputs Low)	17	
		Bn to AOn (outputs High)	14	

### **ORDERING INFORMATION**

PACKAGE	COMMERCIAL RANGE V <sub>CC</sub> = 3.3V±10%; T <sub>amb</sub> = -40°C to +85°C	DWG No.
52-pin Plastic Quad Flat Pack (PQFP)	FBL2033BB	SOT379-1
NOTE: Thermal mounting or forced air is recommended		

### PIN CONFIGURATION



### FBL2033

#### DESCRIPTION

The FBL2033 is an 8-bit transceiver featuring a split input (AI) and output (AO) bus on the TTL-level side.

The common I/O, open collector B port operates at BTL signal levels. The logic element for data flow in each direction is controlled by two pairs of mode select inputs (SBA0 and SBA1 for B-to-A, SAB0 and SAB1 for A-to-B). It can be configured as a buffer, a register, or a D-type latch.

When configured in the buffer mode, the inverse of the input data appears at the output port. In the flip-flop mode, data is stored on the rising edge of the appropriate clock input (LCAB or LCBA). In the latch mode, clock pins serve as transparent-High latch enables. Regardless of the mode, data is inverted from input to output.

Data flow in the B-to-A direction, regardless of the logic element selected, is further controlled by the Loopback input. When the Loopback input is High the output of the selected A-to-B logic element (not inverted) becomes the B-to-A input.

The 3-State AO port is enabled by asserting a High level on OEA. The B port has two output enables, OEB0 and  $\overline{OEB1}$ . Only when OEB0 is High and  $\overline{OEB1}$  is Low is the output enabled. When either OEB0 is Low or  $\overline{OEB1}$  is High, the B-port is inactive and is pulled to the level of the pull-up voltage. New data can be entered in the flip-flop and latched modes or can be retained while the associated outputs are in 3-State (AO port) or inactive (B port).

The B-port drivers are Low-capacitance open collectors with controlled ramp and are designed to sink 100mA. Precision band gap references on the B-port ensure very good noise margins by limiting the switching threshold to a narrow region centered at 1.55V.

The B-port interfaces to "Backplane Transceiver Logic" (see the IEEE 1194.1 BTL standard). BTL features low power consumption

by reducing voltage swing (1V p-p, between 1V and 2V) and reduced capacitive loading by placing an internal series diode on the drivers. BTL also provides incident wave switching, a necessity for high performance backplanes.

Output clamps are provided on the BTL outputs to further reduce switching noise. The "V<sub>OH</sub>" clamp reduces inductive ringing effects during a Low-to-High transition. The "V<sub>OH</sub>" clamp is always active. The other clamp, the "trapped reflection" clamp, clamps out ringing below the BTL 0.5V V<sub>OL</sub> level. This clamp remains active for approximately 100ns after a High-to-Low transition.

To support live insertion, OEB0 is held Low during power on/off cycles to ensure glitch- free B port drivers. Proper bias for B port drivers during live insertion is provided by the BIAS V pin when at a 3.3V level while V<sub>CC</sub> is Low. The BIAS V pin is a low current input which will reverse-bias the BTL driver series Schottky diode, and also bias the B port output pins to a voltage between 1.62V and 2.1V. This bias function is in accordance with IEEE BTL Standard 1194.1. If live insertion is not a requirement, the BIAS V pin should be tied to a V<sub>CC</sub> pin.

The LOGIC GND and BUS GND pins are isolated inside the package to minimize noise coupling between the BTL and TTL sides. These pins should be tied to a common ground external to the package.

Each BTL driver has an associated BUS GND pin that acts as a signal return path and these BUS GND pins are internally isolated from each other. In the event of a ground return fault, a "hard" signal failure occurs instead of a pattern dependent error that may be very infrequent and impossible to trouble- shoot.

As with any high power device thermal considerations are critical. It is recommended that airflow (300lfpm) and/or thermal mounting be used to ensure proper junction temperature.

### **PIN DESCRIPTION**

SYMBOL	PIN NUMBER	TYPE	NAME AND FUNCTION
AI0 – AI7	50, 52, 3, 5, 8, 10, 12, 15	Input	Data inputs (TTL)
AO0 – AO7	51, 2, 4, 6, 9, 11, 14, 16	Output	3-State outputs (TTL)
<u>B0</u> – <u>B7</u>	40, 38, 36, 34, 32, 30, 28, 26	I/O	Data inputs/Open Collector outputs, High current drive (BTL)
OEB0	23	Input	Enables the B outputs when High
OEB1	24	Input	Enables the B outputs when Low
OEA	43	Input	Enables the AO outputs when High
BUS GND	39, 37, 35, 33, 31, 29, 27, 25	GND	Bus ground (0V)
LOGIC GND	1, 13, 17, 49	GND	Logic ground (0V)
V <sub>CC</sub>	18, 22, 48	Power	Positive supply voltage
BIAS V	41	Power	Live insertion pre-bias pin
BG V <sub>CC</sub>	44	Power	Band Gap threshold voltage reference
BG GND	42	GND	Band Gap threshold voltage reference ground
SABn	20, 21	Input	Mode select from AI to B
SBAn	45, 46	Input	Mode select from $\overline{B}$ to AO
LCAB	47	Input	A-to-B clock/latch enable (transparent latch when High)
LCBA	19	Input	B-to-A clock/latch enable (transparent latch when High)
Loopback	7	Input	Enables loopback function when High (from AIn to AOn)

## FBL2033

Product specification

### **FUNCTION TABLE**

					INPUTS	3				Ουτι	PUTS
MODE	Aln	Bn*	OEB0	OEB1	OEA	LCAB	LCBA	SAB <sub>1</sub> 0	SBA <sub>1</sub> 0	AOn	Bn
Aln to Bn thru mode	L	—	Н	L	L	Х	Х	LL	XX	Z	H**
	Н	—	Н	L	L	Х	Х	LL	XX	Z	L
Aln to Bn transparent latch	L	—	н	L	L	н	Х	ΗX	XX	Z	H**
Ain to bir transparent laten	н	—	Н	L	L	н	Х	НX	XX	Z	L
Aln to $\overline{Bn}$ latch and read	I	—	Н	L	L	$\downarrow$	Х	ΗX	XX	Z	H**
AIT to bit later and read	h	—	Н	L	L	$\downarrow$	Х	ΗX	XX	Z	L
Alp to Pp register	L	—	Н	L	L	↑	Х	LH	XX	Z	H**
Aln to Bn register	Н	—	н	L	L	<b>↑</b>	Х	LH	XX	Z	L
Bn outputs latched and read (preconditioned latch)	х	_	н	L	L	L	х	ΗХ	ХХ	Z	latched data
Bn to AOn thru mode	Х	L	L	Н	Н	Х	Х	XX	LL	Н	input
Bir to Aon tinta mode	Х	Н	L	Н	Н	Х	Х	XX	LL	L	input
Bn to AOn transparent latch	Х	L	L	Н	Н	Х	Н	XX	НX	Н	input
Bir to AOII transparent laten	Х	н	L	Н	Н	Х	н	XX	НX	L	input
Bn to AOn latch and read	Х	I	L	Н	Н	Х	$\downarrow$	XX	HX	Н	input
Bir to AOI later and read	Х	h	L	Н	Н	Х	$\downarrow$	XX	НX	L	input
Bn to AOn register	Х	L	L	Н	Н	Х	<b>↑</b>	XX	LH	Н	input
Billo AOI register	Х	Н	L	Н	Н	Х	$\uparrow$	XX	LH	L	input
AOn outputs latched and read (preconditioned latch)	х	х	L	н	н	х	L	ХХ	ΗХ	latched data	х
Disable Bn outputs	Х	Х	L	Х	Х	Х	Х	XX	XX	Х	H**
	Х	Х	Х	Н	Х	Х	Х	XX	XX	Х	H**
Disable AOn outputs	Х	Х	Х	Х	L	Х	Х	XX	XX	Z	Х

### FUNCTION SELECT TABLE

MODE SELECTED	SXX1	SXX0
Thru mode	L	L
Register mode	L	н
Latch mode	н	Х

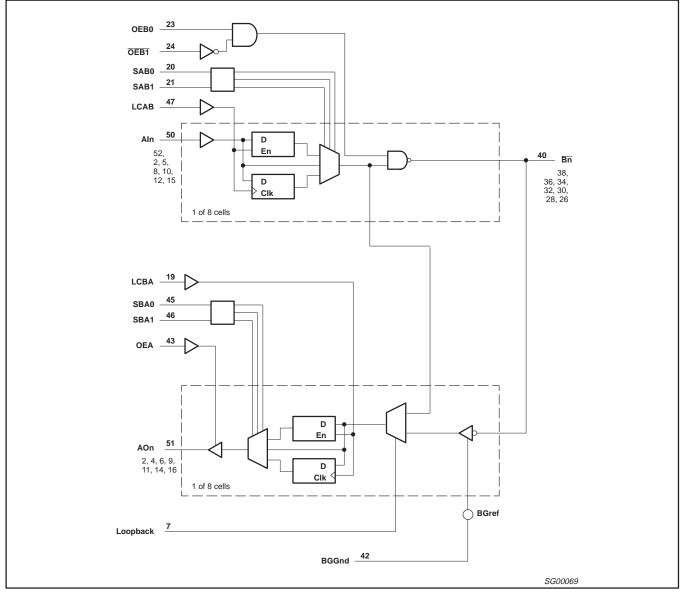
#### NOTES:

T

- H = High voltage level
- L = Low voltage level
- h = High voltage level one set-up time prior to the High-to-Low LCXX transition
- = Low voltage level one set-up time prior to the High-to-Low LCXX transition
- X = Don't care
- Z = High-impedance (OFF) state
- = Input not externally driven
- ↑ = Low-to-High transition
- ↓ = High-to-Low transition
- H\*\* = Goes to level of pull-up voltage
- Bn<sup>\*</sup> = Precaution should be taken to ensure B inputs do not float. If they do, they are equal to Low state. In Loopback mode (Loopback = High), Aln inputs are routed to the AOn outputs. The Bn inputs are blocked out.

### FBL2033

LOGIC DIAGRAM



### **ABSOLUTE MAXIMUM RATINGS**

Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.

SYMBOL	PAR	AMETER	RATING	UNIT	
V <sub>CC</sub>	Supply voltage	Supply voltage			
VIN	Input voltage	AI0 – AI7, OEB0, OEAn		V	
VIN	input voltage	<u>B0</u> – <u>B7</u>	-0.5 to +3.5	1	
I <sub>IN</sub>	Input current	$V_{IN} < 0$	-50	1	
V <sub>OUT</sub>	Voltage applied to output in High outp	out state	-0.5 to +7.0	V	
	Current applied to output in	AO0 – AO7	64, –64	mA	
IOUT	Low output state/High output state	<u>B0</u> – <u>B7</u>	200	] "```	
T <sub>STG</sub>	Storage temperature		-65 to +150	°C	

### FBL2033

### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER			COMMERCIAL LIMITS V <sub>CC</sub> = 3.3V±10%; T <sub>amb</sub> = -40 to +85°C			
			MIN	TYP	MAX		
V <sub>CC</sub>	Supply voltage		3.0	3.3	3.6	V	
Maria	High-level input voltage	Except B0-B7	2.0			V	
VIH		<u>B0</u> – <u>B7</u>	1.62	1.55			
M	V <sub>IL</sub> Low-level input voltage	Except B0-B7			0.8	V	
۷IL		<u>B0</u> – <u>B7</u>			1.47		
I <sub>IK</sub>	Input clamp current				-18	mA	
I <sub>ОН</sub>	High-level output current	AO0 – AO7			-12	mA	
1	Low-level output current	AO0 – AO7			+12	mA	
IOL		<u>B0</u> – <u>B7</u>			100		
C <sub>OB</sub>	Output capacitance on B port			6	7	pF	
T <sub>amb</sub>	Operating free-air temperature range		0		+70	°C	

### LIVE INSERTION SPECIFICATIONS

OVMDOL		PARAMETER		LIMITS		UNIT
SYMBOL		MIN	TYP	MAX		
V <sub>BIASV</sub>	Bias pin voltage	Voltage difference between the Bias voltage and $V_{CC}$ after the PCB is plugged in.	-	-	0.5	V
	Bias pin (I <sub>BIASV</sub> ) input	V <sub>CC</sub> = 0 V, Bias V = 3.6V			1.2	mA
IBIASV DC current		V <sub>CC</sub> = 3.3V, Bias V = 3.6V			10	μΑ
V <sub>Bn</sub>	Bus voltage during prebias	$\overline{B0} - \overline{B7} = 0V$ , Bias V = 3.3V	1.62		2.1	V
I <sub>LM</sub>	Fall current during prebias	$\overline{B0} - \overline{B7} = 2V$ , Bias V = 1.3 to 2.5V			1	μΑ
I <sub>HM</sub>	Rise current during prebias	$\overline{B0} - \overline{B7} = 1V$ , Bias V = 3 to 3.6V	-1			μA
I <sub>Bn</sub> PEAK	Peak bus current during insertion	$V_{CC} = 0$ to 3.3V, $\overline{B0} - \overline{B7} = 0$ to 2.0V, Bias V = 2.7 to 3.6V, OEB0 = 0.8V, t <sub>r</sub> = 2ns			10	mA
	Devuer up eurrent	V <sub>CC</sub> = 0 to 3.3V, OEB0 = 0.8V			100	
I <sub>OL</sub> OFF	Power up current	$V_{CC} = 0$ to 1.2V, OEB0 = 0 to 5V			100	μA
t <sub>GR</sub>	Input glitch rejection	$V_{CC} = 3.3V$	1.0	1.35		ns

#### Product specification

## 3.3V BTL 8-bit latched/registered/pass-thru universal transceiver

FBL2033

### **DC ELECTRICAL CHARACTERISTICS**

Over recommended operating free-air temperature range unless otherwise noted.

symbol	Doromoto		test conditions <sup>1</sup>		limits	_	uni
Symbol	paramete	÷1	lest conditions.	min	typ <sup>2</sup>	max	
I <sub>OH</sub>	High level output current	<u>B0 – B7</u>	$V_{CC} = MAX, V_{IL} = MAX, V_{OH} = 1.9V$			100	μA
	Power-off output current	$\overline{B0} - \overline{B7}$	$V_{CC} = 0V, V_{IL} = MAX, V_{OH} = 1.9V$			100	μ
IOFF	Power-on output current	B0 – B7	$V_{CC} = 0V, V_{IL} = MAX, V_{OH} = 1.9V@85^{\circ}C$			300	Ι <sup>μ.</sup>
.,	High-level output		$V_{CC}$ = MIN to MAX; $I_{OH}$ = -100 $\mu$ A	V <sub>CC</sub> -0.2			V
V <sub>OH</sub>	voltage	AO0 – AO7 <sup>3</sup>	$V_{CC} = MIN; I_{OH} = -8mA$	2.4			\
			$V_{CC} = MIN; I_{OH} = -32mA$	2.0			\
		AO0 – AO7 <sup>3</sup>	$V_{CC} = MIN; I_{OL} = 16mA$			0.4	\
V <sub>OL</sub>	V <sub>OL</sub> Low-level output voltage		$V_{CC} = MIN; I_{OL} = 32mA$			0.5	\
		$\overline{B0} - \overline{B7}$	$V_{CC} = MIN, I_{OL} = 4mA$	0.5			
			$V_{CC} = MIN, I_{OL} = 100mA$	0.75	1.0	1.20	
V <sub>IK</sub>	Input clamp voltage		$V_{CC} = MIN$ , $I_I = I_{IK} = -18mA$		-0.85	-1.2	\
		Control pins $V_{CC} = 3.6V; V_I = V_{CC} \text{ or } 300 \text{mV}$				±1.0	
I, I	Input leakage current	Control/ AI0 – AI7	$V_{CC} = 0V \text{ or } 3.6V; V_{I} = 5.5V$			10	] μ
-		AI0 – AI7	$V_{CC} = 3.6V; V_{I} = V_{CC}$			1	
		Note 4	V <sub>CC</sub> = 3.6V; V <sub>I</sub> = 300mV			-5	1
			$V_{CC} = MAX, V_{I} = 1.9V$	<b></b> 9∨		100	μ
I <sub>IH</sub>	High-level input current	<u>B0 – B7</u>	$V_{CC} = MAX, V_I = 3.5V$ , note 5	100			
			$V_{CC}$ = MAX, $V_{I}$ = 3.75V, Note 5 @ -40°C	100			m
I <sub>IL</sub>	Low-level input current	<u>B0 – B7</u>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.75V			-100	μ
I <sub>OZH</sub>	Off-state output current	AO0 – AO7	$V_{CC} = MAX, V_O = 3V$			5	μ
I <sub>OZL</sub>	Off-state output current	AO0 – AO7	$V_{CC} = MAX, V_O = 0.5V$			-5	μ
I <sub>CCH</sub>	Supply current (total)		$V_{CC} = MAX$ , outputs High		14	31	ſ
I <sub>CCL</sub>	Supply current (total)	B→A	V <sub>CC</sub> = MAX, outputs Low 17			38	1 "
I <sub>CCZ</sub>	Supply current		V <sub>CC</sub> = MAX		22	55	m
I <sub>CCH</sub>			V <sub>CC</sub> = MAX, outputs High		14	32	~
I <sub>CCL</sub>			V <sub>CC</sub> = MAX, outputs Low	9	18	- mA	
I <sub>CCZ</sub>	Supply current		$V_{CC} = MAX$		14	33	m

#### NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operation conditions for the applicable type.

2. All typical values are at  $V_{CC} = 3.3V$ ,  $T_A = 25^{\circ}C$ . 3. Due to test equipment limitations, actual test conditions are  $V_{IH} = 1.8V$  and  $V_{IL} = 1.3V$  for the B side.

 Unused pins are at V<sub>CC</sub> or GND.
For B port input voltage between 3 and 5 volt; I<sub>IH</sub> will be greater than 100mA but the part will continue to function normally (clamping circuit) is active).

FBL2033

SYMBOL	PARAMETER	TEST CONDITION	MIN	TYP	MAX	MIN	MAX	UNIT
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, An to Bn through latch		1.2 1.2	2.7 2.6	4.8 4.3	1.0 1.0	5.3 4.9	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, An to Bn transparent latch		1.3 1.8	3.2 3.7	5.2 5.6	1.0 1.6	6.1 6.3	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, LCAB to Bn latch		2.0 2.3	3.8 4.3	5.8 6.3	1.2 1.8	7.0 7.3	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, LCAB to Bn register		2.1 2.0	3.8 4.3	5.7 6.5	1.4 1.8	6.9 7.3	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, SABX to Bn inverting		1.2 2.3	4.3 5.1	7.6 8.0	1.0 2.0	9.2 8.7	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, SABX to Bn non-inverting		1.8 1.8	4.0 5.0	6.4 8.5	1.1 1.6	8.0 9.8	ns
t <sub>PLH</sub> t <sub>PHL</sub>	OEBn to Bn		1.5 1.6	3.4 3.4	5.4 5.3	1.0 1.0	6.0 7.2	ns

### AC ELECTRICAL CHARACTERISTICS INDUSTRIAL AND COMMERCIAL (A TO B)

### AC ELECTRICAL CHARACTERISTICS INDUSTRIAL AND COMMERCIAL (A TO B)

SYMBOL	PARAMETER	TEST CONDITION	T <sub>amb</sub> =	+25°C, V <sub>CC</sub> R <sub>L</sub> = 16.5Ω	= 3.3V,	$T_{amb} = -40$ $V_{CC} = 3.$ $R_{L} = 7$	UNIT	
			MIN	TYP	MAX	MIN	MAX	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, An to Bn through latch		1.2 1.2	2.8 2.4	4.5 4.0	1.0 1.0	5.7 4.6	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, An to Bn transparent latch		1.4 1.7	3.2 3.5	5.1 5.4	1.0 1.3	6.1 5.9	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, LCAB to Bn latch		2.0 2.2	3.8 4.1	5.6 6.1	1.3 1.6	6.9 7.0	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, LCAB to Bn register		2.0 2.2	3.9 4.1	5.9 6.1	1.2 1.6	7.7 7.0	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, SABX to Bn inverting		1.2 1.8	4.6 4.7	8.6 7.9	1.0 1.6	10.4 8.7	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, SABX to Bn non-inverting		1.3 1.5	4.5 4.6	8.2 8.2	1.0 1.2	10.0 9.1	ns
t <sub>PLH</sub> t <sub>PHL</sub>	OEBn to Bn		1.5 1.5	3.4 3.2	6.0 7.2	1.0 1.0	6.3 7.0	ns

### Product specification

### FBL2033

SYMBOL	PARAMETER	TEST CONDITION	T <sub>amb</sub> =	+25°C, V <sub>CC</sub>	= 3.3V	$T_{amb} = -40$ $V_{CC} = 3.$		
			MIN	TYP	MAX	MIN	MAX	1
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, Bn to An through mode		2.5 3.0	4.5 5.1	6.5 7.3	1.6 2.6	7.8 9.1	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, Bn to An transparent latch		3.4 3.2	5.4 5.4	7.6 7.6	2.2 2.7	9.2 9.3	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, LCAB to An latch		2.1 1.6	3.9 3.3	5.8 5.0	1.3 1.2	7.2 5.9	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, LCAB to An register		1.9 2.3	3.7 4.1	5.7 6.0	1.1 1.8	6.8 7.0	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, SABX to An inverting		2.3 2.5	4.2 4.5	6.4 6.5	1.3 2.0	7.9 7.4	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, SABX to An non-inverting		1.4 1.9	3.9 4.0	8.7 6.1	1.0 1.5	9.8 7.1	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, Aln to AOn loopback		2.4 2.3	4.3 4.4	6.3 6.6	1.6 1.6	8.1 7.6	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay, LPBK to An non-inverting or inverting		2.0 1.3	4.3 4.9	7.0 9.4	1.4 1.5	8.9 11.3	ns
t <sub>PZH</sub> t <sub>PHZ</sub>	Propagation delay, OEA to An		2.4 3.1	4.3 5.3	6.3 7.6	1.9 2.5	7.3 8.9	ns
t <sub>PZH</sub> t <sub>PHZ</sub>	Propagation delay, OEA to An		2.1 1.4	4.0 2.7	6.2 4.4	1.7 1.0	6.9 5.2	ns

### AC ELECTRICAL CHARACTERISTICS INDUSTRIAL AND COMMERCIAL (B TO A)

### FBL2033

### AC SETUP REQUIREMENTS INDUSTRIAL AND COMMERCIAL

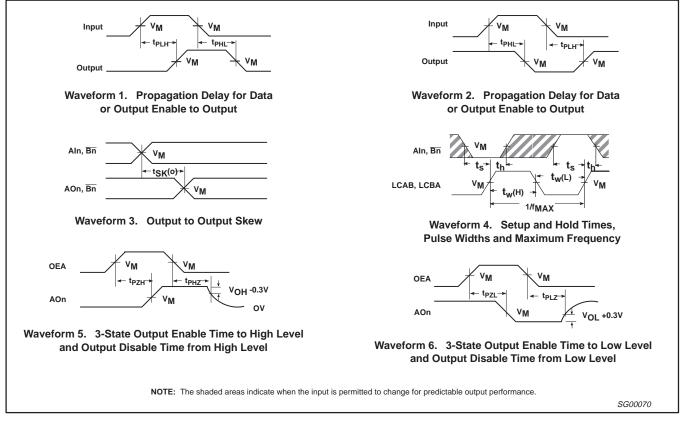
SYMBOL	PARAMETER	TEST CONDITION	LIMITS		
			T <sub>amb</sub> = +25°C, V <sub>CC</sub> = 3.3V	T <sub>amb</sub> = −40 to +85°C, V <sub>CC</sub> = 3.3V±10%	UNIT
			$C_L$ = 50pF (A side) / $C_D$ = 30pF (B side) $R_L$ = 500 $\Omega$ (A side) / $R_U$ = 9 $\Omega$ (B side)		
			MIN	MIN	
t <sub>s</sub> (H) t <sub>s</sub> (L)	Setup time Aln to LCAB or $\overline{Bn}$ to LCBA		3.0 3.0	4.0 4.0	ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time (latch mode) Aln to LCAB		6.0 5.0	6.5 5.5	ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time (register mode) AIn to LCAB		1.0 1.0	1.3 1.3	ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time (latch mode) Bn to LCAB		1.5 1.5	2.0 2.0	ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time (register mode) Bn to LCAB		1.0 1.0	1.3 1.3	ns
t <sub>w</sub> (H) t <sub>w</sub> (L)	Pulse width, High or Low Aln to LCAB or Bn to LCBA		3.0 3.0	4.0 4.0	ns

### AC SETUP REQUIREMENTS INDUSTRIAL AND COMMERCIAL

SYMBOL	PARAMETER	TEST CONDITION	LIMITS		
			T <sub>amb</sub> = +25°C, V <sub>CC</sub> = 3.3V	T <sub>amb</sub> = −40 to +85°C, V <sub>CC</sub> = 3.3V±10%	UNIT
			$C_L$ = 50pF (A side) / $C_D$ = 30pF (B side) $R_L$ = 500 $\Omega$ (A side) / $R_U$ = 16.5 $\Omega$ (B side)		]
			MIN	MIN	
t <sub>s</sub> (H) t <sub>s</sub> (L)	Setup time AIn to LCAB or Bn to LCBA		3.0 3.0	4.0 4.0	ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time (latch mode) Aln to LCAB		6.0 5.0	6.5 5.5	ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time (register mode) Aln to LCAB		1.0 1.0	1.3 1.3	ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time (latch mode) Bn to LCAB		1.5 1.5	2.0 2.0	ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time (register mode) Bn to LCAB		1.0 1.0	1.3 1.3	ns
t <sub>w</sub> (H) t <sub>w</sub> (L)	Pulse width, High or Low AIn to LCAB or Bn to LCBA		3.0 3.0	4.0 4.0	ns

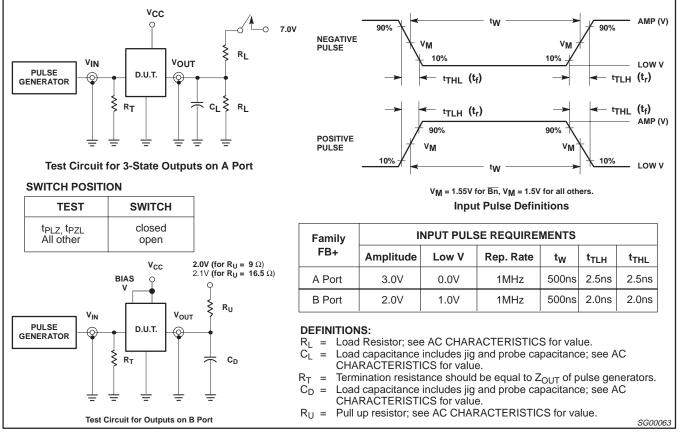
### FBL2033

#### AC WAVEFORMS



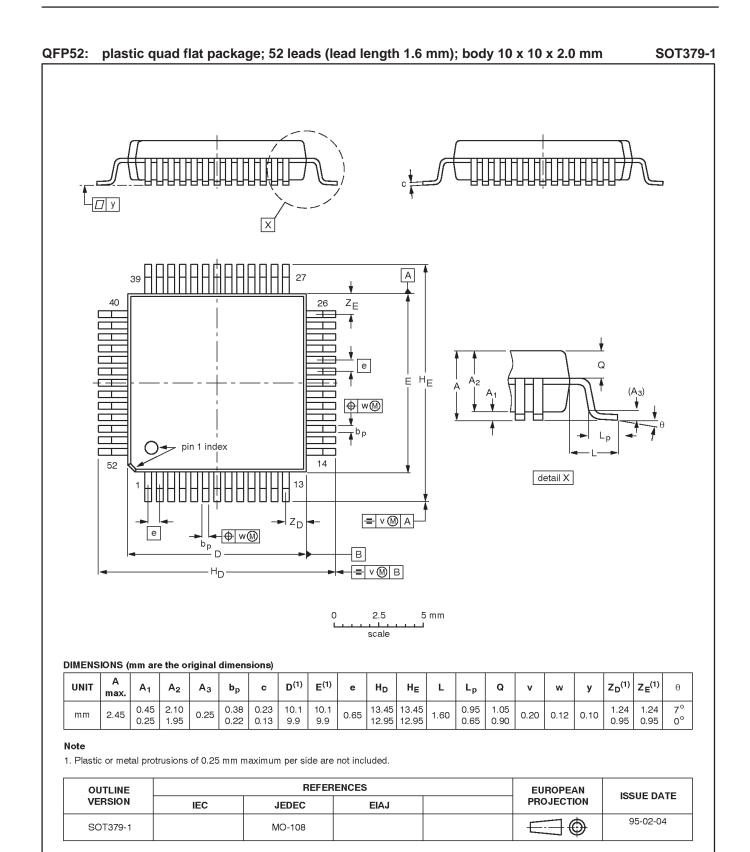
### FBL2033

### TEST CIRCUIT AND WAVEFORMS



## 3.3V BTL 8-bit latched/registered/pass-thru Futurebus+ universal interface transceiver

### FBL2033



## FBL2033

#### Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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[1] Please consult the most recently issued datasheet before initiating or completing a design.

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